

2. A filter arrangement as claimed in claim 1, characterized in that the bandpass filter is connected between the input of the bandpass filter and ground or between the output of the bandpass filter and ground.

3. (Cancelled).

4. A filter arrangement as claimed in claim 1, characterized in that the bandpass filter comprises a filter arrangement of resonators.

5. (Amended) A filter arrangement as claimed in claim 4, characterized in that the filter arrangement comprises bulk acoustic wave resonators, surface acoustic wave resonators, or ceramic electromagnetic resonators.

6. (Amended) A filter arrangement as claimed in claim 5, characterized in that a bulk acoustic wave resonator comprises a resonator unit and a reflection element (2) which is arranged between the substrate (1) and the resonator unit.

7. A filter arrangement as claimed in claim 1, characterized in that the notch filter comprises a capacitor and an inductance.

8. (Thrice Amended) A method of manufacturing a filter arrangement, which comprises a substrate and provided thereon a bandpass filter of bulk acoustic wave resonators and a notch filter, by which method

a second electrode (5), a piezoelectric layer (4), and a first electrode (3) are provided on a carrier layer and are structured such that at least one resonator unit, a capacitor, and an inductance are created,

- a reflection element (2) is deposited on those portions of the first electrode (3) which belong to the resonator unit,

- a substrate (1) is fastened on the entire assembly opposite to the carrier layer, and the carrier layer is removed.